/ Revised record

D	2018-7				
E	2018-10-16				
F	2019-3-13	2		.	
G	2020-1-8	2 3 6	$V_{GS(th)}$! " #$%&'$( ) * + #$, -&'$( ) .V_{GSS} ! " ±20 改为±12V；I_{GSS} 的条件 ! " V_{GS}=±20V 改为 V_{GS}=±12V；		

SOP-8 MOS

Complementary Enhancement MOSFET in a SOP-8 Plastic Package.

N-channel	P-channel
V_{DS}(V)=30V	V_{DS}(V)=-30V
I_D=6.9A	I_D=-6A
$R_{DS(ON)}$<32mΩ (V_{GS}=10V)	$R_{DS(ON)}$<65mΩ (V_{GS}=-10V)
$R_{DS(ON)}$<36mΩ (V_{GS}=4.5V)	$R_{DS(ON)}$<75mΩ (V_{GS}=-4.5V)

Halogen-free Product.

DC/DC

These devices are well suited for high efficiency switching DC/DC converters and switch mode power supplies. And suitable for use as a load switch or in PWM applications.

参数 Parameter	符号 Symbol	数值 Rating		单位 Unit
		N-channel	P-channel	
Drain-Source Voltage	V_{DSS}			

V

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250μA	30	30		

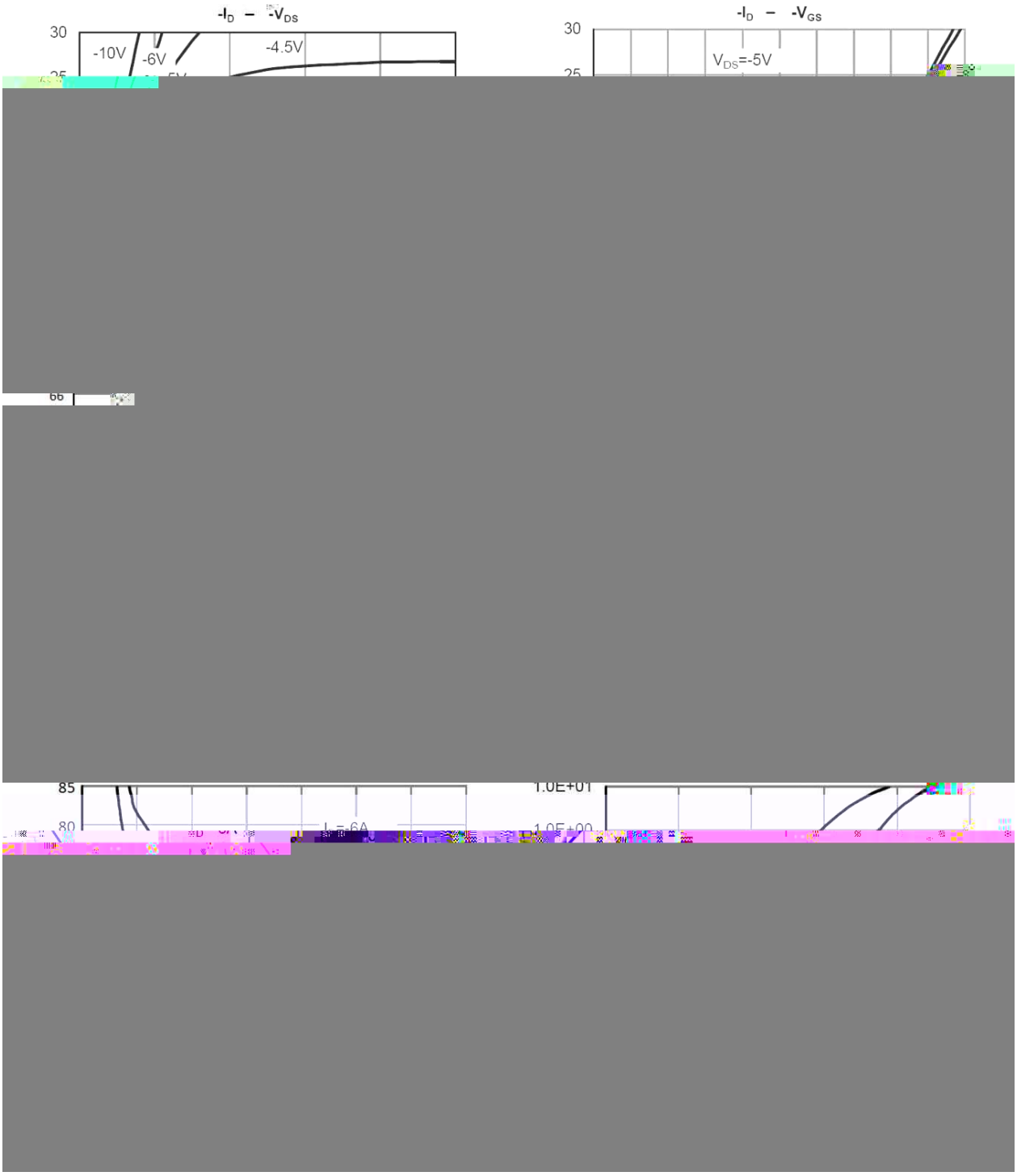
=0V

N- / N-6

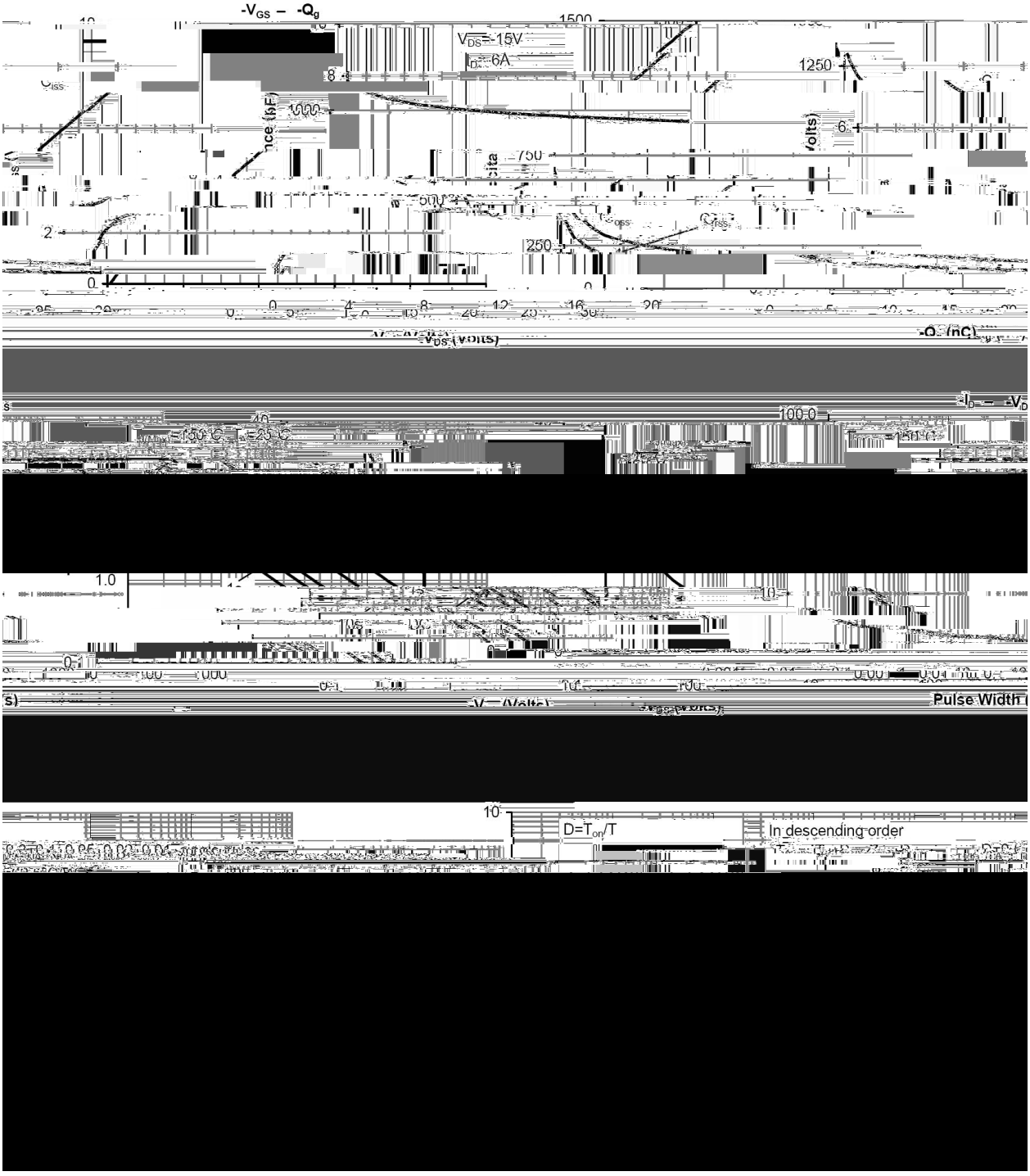
2 N

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}				

P– / P-CHANNEL Electrical Characteristic Curve



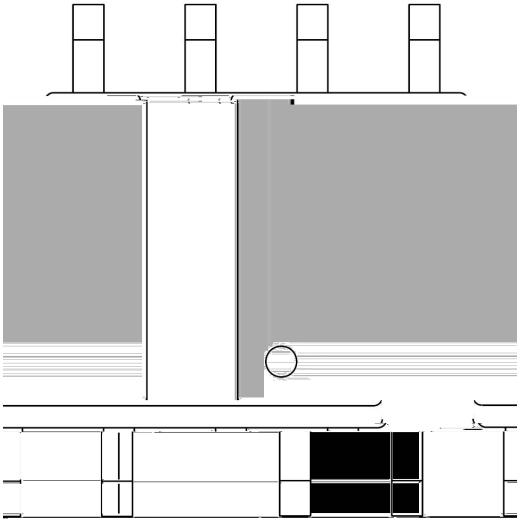
P– / P-CHANNEL Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



					Note:
1	150	180	60	90sec;	1.Preheating:150~180 , Time:60~90sec.
2	245±5				